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# Joint Education for Advanced Chip Design in Europe (Edu4Chip)

## Deliverable Report

## Marketing materials

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# 1 Introduction

This deliverable provides an overview of the marketing and promotional materials developed within the Edu4Chip project.

The development of these materials is based upon a strategy aimed at attracting students and increasing the visibility of the project among academic, industrial, and public stakeholders. Materials include both online and printable formats and were designed to be clear, accessible, and consistent between all partner universities. All materials referenced in this report are available for download on the project website at this [link](#).

To support recognition and consistency of different materials, a visual identity was established. This includes a project logo (shown in Figure 1 and available at this [link](#)), a common color palette (shown in Figure 2), and a set of design elements used across all the materials.

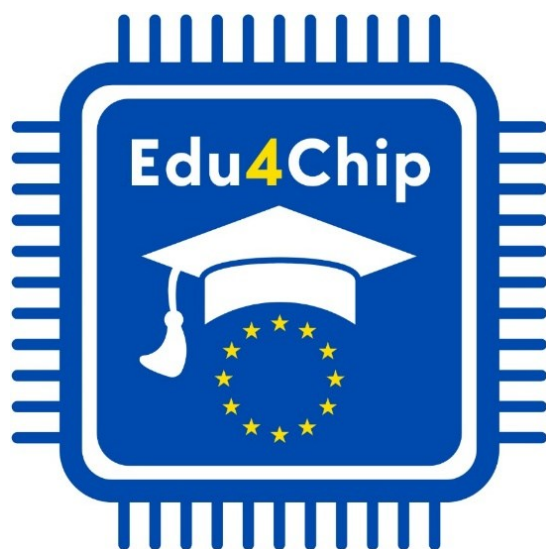


Figure 1. Edu4Chip logo.



Figure 2. Color palette.

The rest of this deliverable is organized into sections dedicated to different types of materials. These include online resources (the project website, university-specific webpages, the Edu4Chip landing page on the EU Digital Skills & Jobs Platform, and selected articles and news), printed materials (brochure, poster, and roll-up banner), promotional content for the Edu4Chip Summer School 2025, events where the program has been presented, and other related materials.

Please note that this deliverable reflects the status of the materials at the time of writing; content is expected to evolve as the project progresses, and new activities are launched.

## 2 Online materials

This section describes the produced online materials.

### 2.1 Project website

The Edu4Chip project website (<https://edu4chip.github.io/>) is the main entry point for students interested in the program. All other marketing materials, such as flyers, posters, and presentations, link to this site via direct URLs or QR codes. Figure 3 shows a screenshot of part of the Edu4Chip homepage.

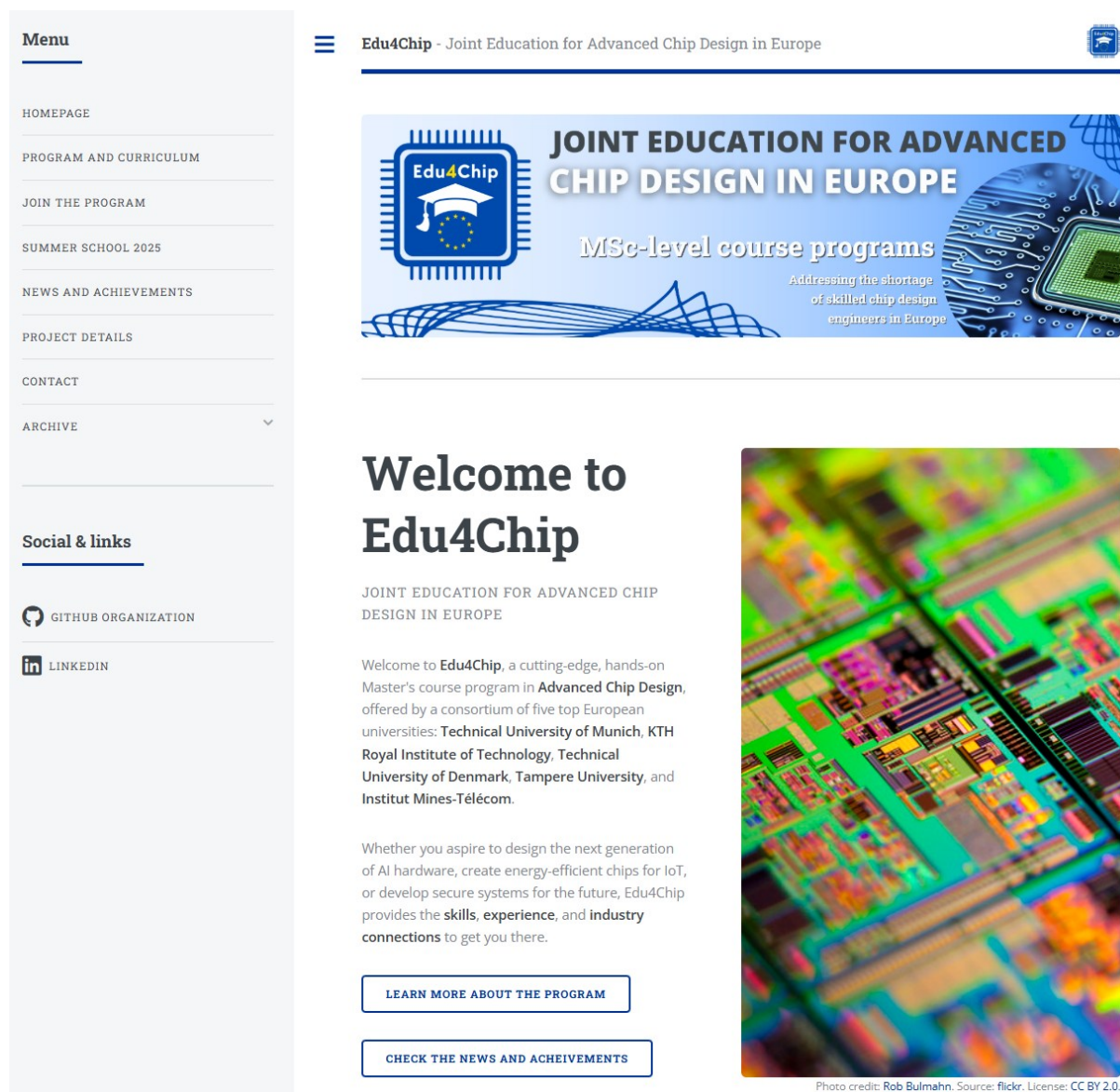


Figure 3. A screenshot of part of the Edu4Chip homepage.

The website aims to provide an overview of the project and the program at the different partner universities and links to university-specific program pages, where students can find detailed and localized

information about course offerings and application/enrollment procedures at each partner institution. In addition, the website includes pages dedicated to the summer schools and other events organized within the project scope, as well as links to our LinkedIn page and GitHub organization.

The website also serves as a resource for academic, industrial, and public stakeholders (including policymakers). In this regard, the webpage also presents the project's goals, key contacts, news, outcomes, and achievements.

The Edu4Chip website is hosted using GitHub Pages. The website is built with a responsive design, ensuring that all pages are accessible and readable across a range of devices (desktops, tablets, and mobile phones). Figure 4 shows the sitemap for the project website.

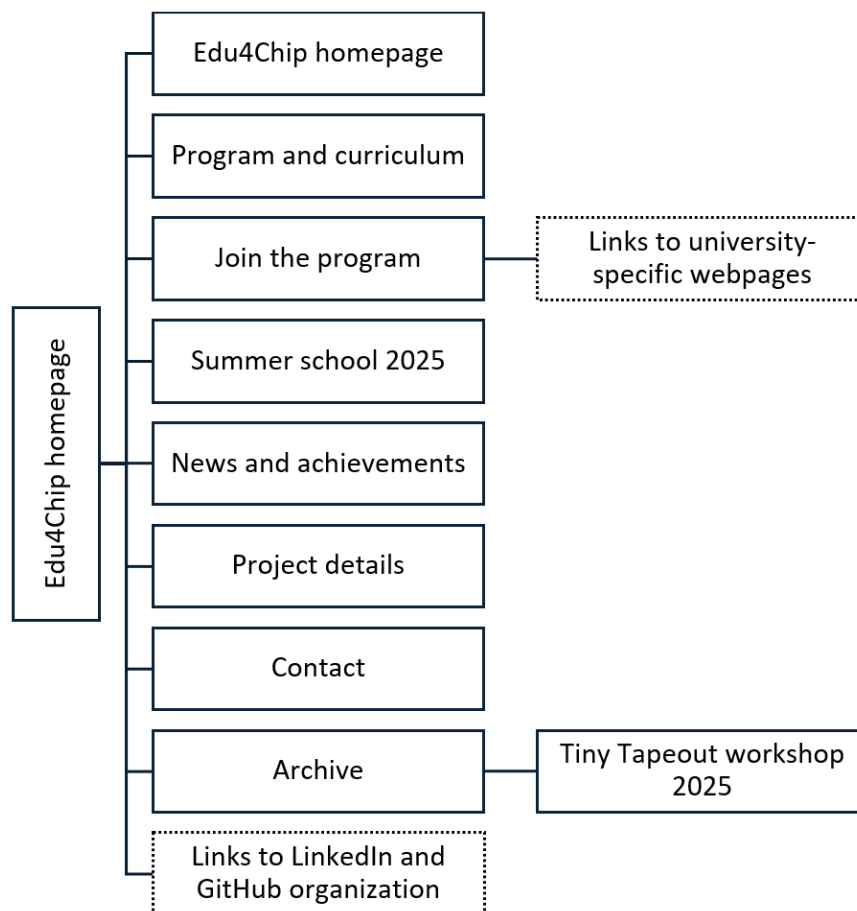


Figure 4. Project website sitemap.

The content of each page of the project website is briefly described below to provide an overview of how information is currently presented.

- **Edu4Chip homepage:** The page welcomes the user and offers a general introduction to the program, outlining its goals, core activities, and collaborative nature. It highlights the program's focus on practical learning (real tapeout chip design project), cross-institutional cooperation and exchange, and links to industry. The page also lists the participating universities and partners involved in the initiative.

- **Program and curriculum:** The page outlines the overall structure and educational approach of the program. It highlights how the program is implemented across partner universities and the opportunities for international exchange. The page also gives an overview of the main curriculum components and links to a detailed version of the curriculum. The aim is to help students understand the overall learning paths and technical focus.
- **Join the program:** The page provides a brief description of how the Edu4Chip program is implemented at each partner university and includes direct links to the university-specific program pages (as external links) and contacts at each institution.
- **Summer school 2025:** The page offers information regarding the first Edu4Chip summer school, held in August 2025 at the Technical University of Denmark. It includes an overview, practical information, program and content, and contact information. Similar pages will be created for future editions.
- **News and achievements:** The page lists the project's news, achievements, and outcomes, as well as updates on project activities. For example, the page includes links to external news where Edu4Chip is featured, public deliverables from the project, and, when ready, will also include links to related publications.
- **Project details:** The page outlines the overall scope of the project, including objectives, funding period, and consortium partners. It provides context for how the program fits into a broader European initiative.
- **Contact:** Provides the main contacts for the project.
- **Archive:** This section holds pages of past activities and initiatives. Currently, it has only one entry dedicated to a hands-on workshop held at DTU in February 2025. This can be useful for those interested in similar future activities or looking for examples of the program in action.

## 2.2 University-specific webpages

Each partner university in Edu4Chip hosts its own dedicated webpages dedicated to local implementation of the program or specialization. These pages provide university-specific detailed information about admission requirements, application procedures, course content, structure, and relevant contacts.

The links to the university-specific webpages are listed below. These are also linked from the Edu4Chip project website ("Join the program" page):

- TUM: [Master in Microelectronics and Chip Design](#)
- KTH: [Master's Programme in Embedded Systems \(Embedded Electronics track\)](#)
- DTU: [MSc in Computer Science and Engineering \(Digital Systems Specialization\)](#)
- TAU: [MSc in System-on-Chip Design](#)
- IMT: [Specialized Master's Degree in Microelectronic Circuit Design](#)

## 2.3 EU Digital Skills & Jobs Platform pages

Edu4Chip is featured on the EU Digital Skills & Jobs Platform with a dedicated landing page at this [link](#). The page briefly introduces the project scope, its objectives, and lists the partners and associated partners.

In the near future, we also plan to add to the EU Digital Skills & Jobs Platform the Lifelong Learning modules offered as part of the Edu4Chip offering by the partner universities. These modules are expected to be offered during the third and fourth years of the project.

## 2.4 Articles and news

Edu4Chip was featured in the articles and news listed below. The articles highlight the key activities, and although not direct marketing materials, they contribute towards promoting the program by raising awareness and showcasing the project's relevance.

- DTU: Chip innovation and education at DTU Compute ([link to article](#))
- DTU: DTU Chip Day because Industry and Europe need students for chip design ([link to article](#))
- DTU: Great interest in a four-hour chip design workshop ([link to article](#))
- TAU: Article on Edu4Chip at SoC Hub ([link to article](#))

## 2.5 Social media presence

A LinkedIn page dedicated to the Edu4Chip project was launched in June 2025. This timing is according to plan and aims to have the social media presence established in advance of the first semester of the programs and specializations in September/October 2025.

LinkedIn was chosen as it best fits our target audience of students, academics, and industry. The use of other platforms (i.e. Instagram) may be considered in the future if needed.

The Edu4Chip LinkedIn page is intended to serve as a platform for sharing project news, outcomes, and project developments. We also plan to highlight student success stories, personal experiences, and educational achievements within the program.

The LinkedIn page can be accessed at this [link](#), and it is also linked directly from the project webpage.



## 3 Printable materials

This section describes the produced printable materials.

### 3.1 Brochure

The brochure aims to offer a quick overview of the benefits of the Edu4Chip initiative and directs readers to the project website for more information (accessible via link and QR code). The brochure is A4 in size and is Z-folded, as shown in Figure 5. The brochure is common for all Edu4Chip partners and is intended for distribution at events. Each partner is responsible for independent printing and distribution.



Figure 5. The Z-folded brochure.

The brochure consists of six panels. The layouts and content of the exterior (front) and interior sides of the brochure are shown in Figure 6 and Figure 7, respectively. The high-resolution brochure files are available at this [link](#).

### 3.2 French-language brochure

In addition to the common brochure in English, IMT developed a French-language version to support local outreach. It presents IMT's program's structure, admission process, and program content. The brochure is available at this [link](#).



## WHAT YOU'LL ACHIEVE

### KNOWLEDGE

Gain deep insights into the entire chip design flow, from concept to production.

### SKILLS

Design and produce your own chip during your studies. Gain hands-on experience at every step of the process.

### CONNECTIONS

Collaborate with academia and industry experts, address real-world challenges, and stay at the forefront of chip design innovations.



Photo credit: Bax Lindhardt

## CAREER FOCUS

- Chip design engineer
- AI hardware architect
- Low-power design specialist
- Secure hardware designer

## MEET OUR PARTNERS

### UNIVERSITIES

**TUM** Technical University of Munich  
Germany

**KTH** Royal Institute of Technology  
Sweden

**DTU** Technical University of Denmark  
Denmark

**Tampere University**  
Finland

**Institut Mines-Télécom**  
France

### INDUSTRY

**LogiqWorks**, Bulgaria  
**MINRES**, Germany  
**SyoSil**, Denmark  
**Fraunhofer IIS**, Germany

**SyoSil** Systems on Silicon  
**Fraunhofer**

### ASSOCIATED PARTNERS

**VLSI Solution OY**, Finland  
**Infineon Technologies AG**, Germany  
**Texas Instruments Deutschland GmbH**, Germany

## BECOME A CHIP DESIGN EXPERT WITH Edu4Chip



### JOINT EDUCATION FOR ADVANCED CHIP DESIGN IN EUROPE



Photo credit: Rob Buimans  
Source: flickr. Cropped. License: CC BY 2.0

**Master-level course programs**  
offered by the universities  
**TUM, KTH, DTU, TAU, and IMT**

Figure 6. Content of the exterior (front) of the brochure.

## WHAT IS Edu4Chip?

Edu4Chip is a European collaborative initiative designed to train the next generation of chip designers through innovative, hands-on Master's programs.

### ALIGNED PROGRAMS

Join a Master's program focused on chip design at one of the partner universities. Gain expertise in digital and analog design, and learn to design, build, and test real chips.

### CHIP TAPEOUT PROJECTS

Go beyond simulations: design, manufacture, and test your own chip! Edu4Chip's hands-on tapeout projects give you practical skills that set you apart in chip design.

### INTERNATIONAL EXCHANGE

Study abroad at one of the partner universities through Edu4Chip's aligned exchange programs, with support from the project and Erasmus+.

### INDUSTRY COLLABORATION

Connect with Europe's top semiconductor companies! Learn from industry experts through guest lectures, real-world projects, and Master's theses to launch your career.

## THE PROGRAM

### BUILD YOUR FOUNDATION

- Digital and analog design essentials
- Computer architecture
- Front-end chip design

### GAIN ADVANCED SKILLS

- Back-end design
- Physical design
- Verification and testing

### MASTER'S THESIS

- Research topic at the university
- Forefront technology in industry



Photo credit: Bax Lindhardt

## Make your own chip with Edu4Chip!

## READY TO GET STARTED?

To get more information scan the QR



or visit  
**edu4chip.github.io**

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Figure 7. Content of the interior (back) of the brochure.

### 3.3 Poster and roll-up banner

The poster and roll-up banner are designed to give an overview of the project title, scope, and partners, and aim to attract attention at events, prompting students and stakeholders to get in touch, take a brochure, and visit the project website for more details (using the QR code). The poster and roll-up banner can also be used at events organized and supported by the project (e.g., the summer school).

Similar to the brochure, both the poster and the roll-up banner are meant to be printed independently by each partner. Their layouts can be seen in Figure 8 and Figure 9, respectively. The poster and roll-up banner in different graphic formats are available at this [link](#).



Figure 8. Poster.



Figure 9. Roll-up banner.



## 4 Promotion of the Edu4Chip Summer School 2025

The first edition of the Edu4Chip Summer School will be held in August 2025 at the Technical University of Denmark.

The marketing materials for the summer school included the A3-sized flyer shown in Figure 10 and a promotional slide (available in three variations, one of which is shown in Figure 11). These are also available at this [link](#).

All materials forward students through links or QR codes to the summer school webpage in the project website for full details about the program, schedule, and application process.

The marketing campaign targeted both students from the partner universities as well as external students. For university partners, the materials were distributed through institutional student communication channels to reach BSc and MSc students. To attract external students, the materials were shared via individual contacts and mailing lists from previous international projects.

This marketing effort proved effective, resulting in 225 applications from partner universities and 29 applications from external students.



Figure 10. Edu4Chip summer school 2025 promotional flyer (A3 format).



**Edu4Chip Summer School on Chip Design**

**Dates**

- One online intro-day: August 11, 2025
- Five in-person days: August 18–22, 2025

**Location**

- Technical University of Denmark, Copenhagen

**Who should attend?**

- BSc and MSc students looking to expand their knowledge in chip design

***Kickstart your journey in chip design!***

**What you will gain**

- Foundational knowledge of chip design workflows
- Practical experience with tools and methodologies
- Insights into the latest semiconductor developments

Organized by the Technical University of Denmark

Partners:

**DTU** **KTH** **MINES Saint-Etienne** **TUM** **Tampere University** **LOGIX WORKS** **MINRES TECHNOLOGIES** **SyoSil** **Fraunhofer**

For more details scan the QR

Or go to: [edu4chip.github.io/summer2025.html](https://edu4chip.github.io/summer2025.html)

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Photo credit: DTU

Figure 11. Edu4Chip summer school 2025 promotional slide (also available in two other variations).

## 5 Events and outreach

As part of the outreach and marketing strategy, the partners have actively promoted the program through a variety of academic, industrial, and student-focused events. These activities play an important role in attracting student interest and raising awareness. The events include technical workshops, conferences, recruitment fairs, and informational webinars. The events are listed below.

- **April 2025:** DTU presented the project at the DTU's Annual Chip Day ([link to the event page 1](#), [link to the event page 2](#)). The slide set used is available at this [link](#).
- **March 2025:** TUM hosted an online webinar aimed at informing potential students about the program structure and admission procedures.
- **February 2025:** DTU organized and hosted a Tiny Tapeout Workshop, which brought together more than 80 participants from academia, industry, and student communities for hands-on learning in chip design ([link to the event page](#)). A promotional flyer for the event is available at this [link](#).
- **January 2025:** IMT hosted an online webinar aimed at informing potential students about the program structure and admission procedures. The slide set used is available at this [link](#).
- **October 2024:** DTU showcased the project at the Nordic IoT Hub Annual Meeting. The slide set used is available at this [link](#).
- **June 2024:** DTU presented the project at the Free Silicon Conference 2024 (FSiC 2024) ([link to the presentation and video recording](#))
- **June 2024:** SyoSil gave a technical talk at the Free Silicon Conference (FSiC 2024) focusing on open-source verification ([link to the presentation and video recording](#)).
- **May 2024:** TUM presented Edu4Chip at the Conference on Computing Frontiers 2024 (CF' 24) ([link to the event program](#), [link to the abstract](#) ).
- IMT participated in seven student and industrial fairs to advertise the Edu4Chip Master's programs. The details of these events are listed in the following.
  - November 2024: Salon Focéen, Marseille
  - November 2024: Salon Perspectives, Lyon
  - January 2025: Salon de l'Etudiant Masters, Mastère spécialisé et premier emploi, Paris
  - February 2025: Salon de l'Etudiant Masters, Mastère spécialisé et premier emploi, Lyon
  - March 2025: Salon de l'Etudiant des métiers et de l'alternance, Marseille)
  - March 2025: Salon de l'Etudiant apprentissage et alternance, Lyon
  - March 2025: Salon Global Industrie, Lyon

In addition to external outreach, we actively promoted Edu4Chip within the university partner BSc and MSc courses. In this way, we target students who are already well-positioned to continue into the Edu4Chip program and specializations. An example of slides used for this purpose is available at this [link](#).

## 6 Related materials

In addition to the common marketing materials directly developed within the Edu4Chip project, some partner universities have developed additional materials. While these materials were not produced under the Edu4Chip project, they still contribute to promoting the new education programs and specializations. A sample of these materials is listed below.

- **Postcard and poster by TUM:** Designed by a third-party agency, these materials advertise TUM's new Master's program in chip design. The postcard and poster files are available at this [link](#).
- **Promotional video by TUM:** A short advertisement clip produced by the TUM public relations team, highlighting their new Master's program in Microelectronics and Chip Design ([link to video](#)).
- **Promotional video by IMT:** A short advertisement clip produced by IMT dedicated to their new program ([link to video](#)).
- **DAAD program listing by TUM:** The Master's program is also featured on the DAAD (German Academic Exchange Service) platform ([link to DAAD page](#)).

## 7 Summary

The deliverable presented an overview of the marketing and promotional materials developed to support the Edu4Chip project's goals of attracting students and increasing visibility across academic, industrial, and public stakeholders.

The document covered the establishment of a unified visual identity, the development of online and printed materials, and the use of targeted communication strategies, including promotion of the Edu4Chip Summer School and active presence at relevant events. It also acknowledged related initiatives by partner institutions that, while independently developed, contribute to the marketing goals.

***Note on transparent use of AI technologies:*** AI-based tools, including Grammarly and GPT-4o, have been used for language refinement and quality/grammar/syntax improvement.